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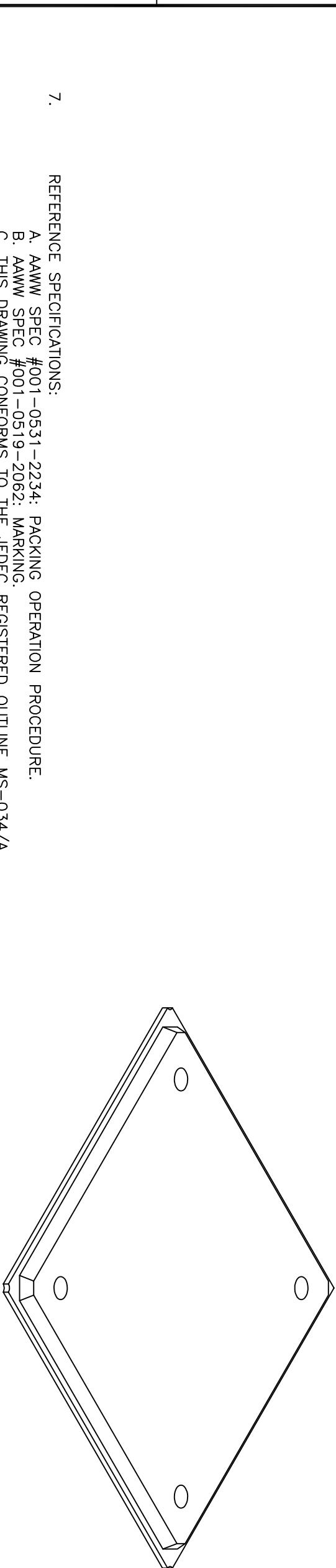
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REVISION HISTORY							
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GERBER FILE NAME	INCORPORATOR	DATE
00	A44863	INITIAL RELEASE	THUANG	N/A	N/A	THUANG	10/13/99
01	A48943	ADDED 580 & 680 FOOTPRINT	SHPAK	N/A	N/A	SHPAK	09/25/00
02	C17076	CAP TOLERANCE WAS 33.70 +0.50/-0.05 AVAILABLE MARKING AREA WAS 30.60 ADDED 6 LYR TO SCHEDULE, NEW FORMAT	DARNO	N/A	N/A	DARNO	06/28/02



7. REFERENCE SPECIFICATIONS:
- A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
 - B. AAWW SPEC #001-0519-2062: MARKING.
 - C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A VARIATION AAR-1.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 1156.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 34 X 34.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		Ankor Technology, Inc. Chandler, Arizona, USA Anam Semiconductor, Inc., Seoul, Korea Ankor Technology Philippines, Inc. Manila, Philippines		
DECIMAL X.X ±0.1	ANGULAR ±1°	APPROVALS	DATE	 ANAM Semiconductor		
X.XX ±0.05		DESIGNED D. ARNOLD	08/02/99			
X.XXX ±0.030		CHECKED M. CUMMINS	08/02/99			
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994		PRODUCT MANAGER D. ARNOLD	08/02/99	TITLE PACKAGE OUTLINE - PBGA CUSTOM, 34 X 34 MATRIX, 35.00mm X 35.00mm, 33.70mm X 33.70mm X 1.17mm MOLD CAP, 1.00mm PITCH, LAMINATE SUBSTRATE, AWW		
MATERIAL SEE CROSS SECTION		RELEASED SO. KANG	10/13/99			
FINISH SEE NOTE 1		SIZE A3		SID NUMBER N/A	DWG NUMBER 75876	REV 02
DO NOT SCALE DRAWING		STRIP DWG NUMBER/REV N/A		PKG OUTLINE DWG NO. N/A	SCALE NONE	SHEET 1 OF 4